

1 ABSTRACT OF THE DISCLOSURE

 A method of fabricating a semiconductor
device includes a step of attaching a circuit
substrate on a semiconductor wafer in alignment with
5 each other, providing an electrical interconnection
between the circuit substrate and semiconductor
devices formed in the wafer, providing solder bumps on
the circuit substrate, and dicing the semiconductor
10 wafer together with the circuit substrate thereon
along a scribe line.

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